

INFORMATION DISCLOSURE STATEMENT

Applicant : Camm, et al.
App. No : 10/005,186
Filed : December 4, 2001
For : HEAT-TREATING METHODS AND
SYSTEMS
Examiner : Fuqua, Shawntina
Art Unit : 3742

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Enclosed for filing in the above-identified application is an Information Disclosure Statement by Applicant (PTO/SB/08 equivalent) listing 15 references to be considered by the Examiner. Also enclosed are 11 foreign patent references and/or non-patent literature as listed on the Information Disclosure Statement.

This Information Disclosure Statement is being filed after the mailing date of a final action or after the mailing date of a Notice of Allowance. This Statement is accompanied by the fee set forth in 37 C.F.R. § 1.17(p). The Commissioner is hereby authorized to charge any additional fees which may be required or to credit any overpayment to Account No. 11-1410.

CERTIFICATION UNDER 37 C.F.R. § 1.97(e)(1)

I hereby certify that each item of information contained in this Statement was first cited in a communication from a foreign Patent Office in a counterpart foreign application not more than three months days/months prior to the filing of this Information Disclosure Statement.

Respectfully submitted,

KNOBBE, MARTENS, OLSON & BEAR, LLP

Dated: Mar. 10, 2005

By: Che S. Chereskin

Che Swyden Chereskin, Ph.D.

Registration No. 41,466

Agent of Record

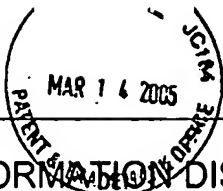
Customer No. 20,995

(949) 760-0404

03/15/2005 RFEKADU1 00000024 10005186

01 FC:1806

180.00 DP



PTO/SB/08 Equivalent

INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Multiple sheets used when necessary)	Application No.	10/005,186	
	Filing Date	December 4, 2001	
	First Named Inventor	Camm, et al.	
	Art Unit	3742	
SHEET 1 OF 1		Examiner	Fuqua
		Attorney Docket No.	FETHE24.001CP1

U.S. PATENT DOCUMENTS					
Examiner Initials	Cite No.	Document Number Number - Kind Code (if known) Example: 1,234,567 B1	Issue Date MM-DD-YYYY	Name of Patentee or Applicant	Pages, Columns, Lines Where Relevant Passages or Relevant Figures Appear
STF		4,325,006	04/13/82	Morton	
		5,777,437	07/07/98	Neister	
STF		6,066,516	05/23/00	Miyasaka	
		6,187,616	02/13/01	Gyoda	

FOREIGN PATENT DOCUMENTS						
Examiner Initials	Cite No.	Foreign Patent Document Country Code-Number-Kind Code Example: JP 1234567 A1	Publication Date MM-DD-YYYY	Name of Patentee or Applicant	Pages, Columns, Lines Where Relevant Passages or Relevant Figures Appear	T ¹
STF		EP 0 105 230	04/11/84	General Electric Company		
		EP 0 538 874	04/28/93	F.T.L. Co., Ltd.		
		GB 2 199 693	07/13/88	Noblelight Ltd		
		JP 01-246828 Abstract	10/02/89	Tokyo Electron Ltd.		✓
		JP 04-355911 Abstract	12/09/92	Fujitsu Ltd		✓
		JP 07-245274 Abstract	09/19/95	Tokyo Electron Ltd		✓
		JP 08-107113 Abstract	04/23/96	Sony Corp		✓
		JP 58-070536 Abstract	04/27/83	Fujitsu Ltd		✓
		JP 58-106836 Abstract	06/25/83	Hitachi Ltd		✓
		JP 59-211221 Abstract	11/30/84	Nippon Denso Co Ltd		✓
STF		WO 99/41777	08/19/99	Seiko Epson Corporation		Abstract Only

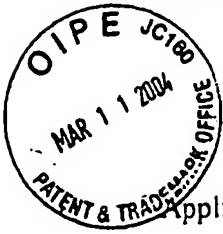
NON PATENT LITERATURE DOCUMENTS			
Examiner Initials	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ¹

1329995_1
030905

Examiner Signature <i>Shauntina Fuqua</i>	Date Considered <i>4/20/05</i>
*Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.	

T¹ - Place a check mark in this area when an English language Translation is attached.

3742



INFORMATION DISCLOSURE STATEMENT

Applicant : Camm, et al.
 App. No. : 10/005,186
 Filed : December 4, 2001
 For : HEAT-TREATING METHODS AND SYSTEMS
 Examiner : S Fuqua
 Group Art Unit : 3742

RECEIVED

MAR 17 2004

TECHNOLOGY CENTER R3700

Commissioner for Patents
 P.O. Box 1450
 Alexandria, VA 22313-1450

Dear Sir:

Enclosed is form PTO-1449 listing 16 references that are also enclosed.

This Information Disclosure Statement is being filed before the receipt of a first Office Action on the merits, and presumably no fee is required in accordance with 37 C.F.R. § 1.97(b)(3). If a first Office Action on the merits was mailed before the mailing date of this Statement, the Commissioner is authorized to charge the fee set forth in 37 C.F.R. § 1.17(p) to Deposit Account No. 11-1410.

Respectfully submitted,

KNOBBE, MARTENS, OLSON & BEAR, LLP

Dated: March 8, 2004

By: Che S. Chereskin

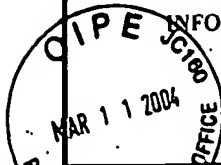
Che Swyden Chereskin, Ph.D.

Registration No. 41,466

Agent of Record

Customer No. 20,995

(949) 760-0404

	INFORMATION DISCLOSURE CITATION (Use several sheets if necessary)	
	Atty. Docket No. FETHE24.001 CP1 (47753-5cip)	Serial No. 10/005,186
	Applicant(s) David M. Camm, et al.	
Filing Date December 4, 2001		Group

U.S. PATENT DOCUMENTS

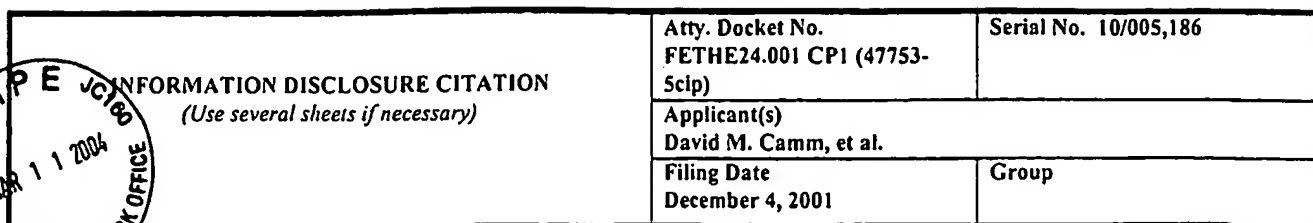
OTHER ART (including Author, Title, Date, Pertinent Pages, Etc.)

3/8	AI	Lord, H.A., "Thermal and Stress Analysis of Semiconductor Wafers in a Rapid Thermal Processing Oven", (August 1988), Vol. 1, No. 3, IEEE Transactions on Semiconductor Manufacturing, p. 105-114.
	AJ	Hill, C., et al., "Rapid Thermal Annealing - Theory and Practice", in <i>Reduced Thermal Processing for VLSI</i> , (New York: Plenum, 1989), p. 143-180.
	AK	Kakoschke, R., "Is There a Way to a Perfect Rapid Thermal Processing System?", (1991), Vol. 224, Mat. Res. Soc. Symp. Proc., p. 159-170.
	AL	Kakoschke, R., et al., "Simulation of Temperature Effects During Rapid Thermal Processing", (1989), Vol. 146, Mat. Res. Soc. Symp. Proc., p. 473-482.
	AM	Vandenabeele, P., et al., "Impact of Patterned Layers on Temperature Non-Uniformity During Rapid Thermal Processing for VLSI-Applications", (1989), Vol. 146, Mat. Res. Soc. Symp. Proc., p. 149-160.
	AN	Nulman, J., et al., "Pyrometric Emissivity Measurements and Compensation in an RTP Chamber", (1989), Vol. 146, Mat. Res. Soc. Symp. Proc., p. 461-466.
	AO	Dilhac, J-M., et al., "Adaptive Process Control for a Rapid Thermal Processor", (1990), SPIE Vol. 1393, Rapid Thermal and Related Processing Techniques, p. 395-403.
3/8	AP	Dilhac, J-M., et al, "Thermal Model for Rapid Thermal Processors: Theory and Applications", (1993), RTP '93 conference proceedings, p. 12-18.

EXAMINER Gheorghina Iugua	DATE CONSIDERED 4/20/05
------------------------------	----------------------------

*EXAMINER:

Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

[illegible][illegible]

AF	Wilson, S.R., et al., "An Overview and Comparison of Rapid Thermal Processing Equipment: A Users Viewpoint", (1986), Vol. 52, Mat. Res. Soc. Symp. Proc., p. 181-190.
AG	Blake, Julian, et al., "Slip Free Rapid Thermal Processing", (1987), Vol. 92, Mat. Res. Soc. Symp. Proc., p. 265-272.
AH	Celler, G.K., et al., "Drift of Arsenic in SiO ₂ in a Lamp Furnace with a Built-in Temperature Gradient", (1987), Vol. 92, Mat. Res. Soc. Symp. Proc., p. 53-58.
EXAMINER	DATE CONSIDERED

Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

3742
JFW

INFORMATION DISCLOSURE STATEMENT

Applicant : Camm, et al.
App. No. : 10/005,186
Filed : December 4, 2001
For : HEAT-TREATING METHODS AND SYSTEMS
Examiner : Fuqua, Shawntina T.
Group Art Unit : 3742

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Enclosed is form PTO-1449 listing two (2) references that are also enclosed. These references have recently come to the attention of Applicant. While we do not believe that these references qualify as prior art under 35 U.S.C. § 102 or 103, out of abundance of caution, Applicant submits these two references and requests that they be considered and made of record in the application.

This Information Disclosure Statement is being filed before the mailing date of a final action under 37 C.F.R. § 1.113 and before the mailing date of a Notice of Allowance under § 1.311. A certification under 37 C.F.R. § 1.97(e) is set forth below. Thus, no fee is required as set forth in 37 C.F.R. § 1.97(c).

CERTIFICATION UNDER 37 C.F.R. § 1.97(e)(2)

I hereby certify that no item of information contained in this Statement was cited in a communication from a foreign Patent Office in a counterpart foreign application, and, to my knowledge after making reasonable inquiry, was known to any individual designated in 37 C.F.R. § 1.56(c) more than 3 months prior to the filing of this Information Disclosure Statement.

Respectfully submitted,

KNOBBE, MARTENS, OLSON & BEAR, LLP

Dated: Sept. 2, 2004

By: Che S. Chereskin
Che Swyden Chereskin
Registration No. 41,466
Agent of Record
Customer No. 20,995
(949) 760-0404

FORM PTO-1449

U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICEATTY. DOCKET NO.
FETHE24.001CP1APPLICATION NO.
10/005,188INFORMATION DISCLOSURE STATEMENT
BY APPLICANT

(USE SEVERAL SHEETS IF NECESSARY)

APPLICANT:
Camm, et al.FILING DATE
December 4, 2001GROUP
3742

U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (IF APPROPRIATE)
all	1	US2004/0105670 A1	6/3/04	Kusuda, et al.	—	—	
304	2	US2004/0112890 A1	6/17/04	Kusuda, et al.	—	—	
	3						
	4						
	5						
	6						
	7						
	8						
	9						
	10						

FOREIGN PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
	11							
	12							
	13							
	14							
	15							
	16							

EXAMINER INITIAL	OTHER DOCUMENTS (INCLUDING AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.)	
	17	
	18	
	19	
	20	
	21	

H:\DOCS\CSC\CSC-7665.DOC
090204

EXAMINER	<i>Shawntina Sugua</i>	DATE CONSIDERED	<i>4/20/05</i>
*EXAMINER: INITIAL IF CITATION CONSIDERED, WHETHER OR NOT CITATION IS IN CONFORMANCE WITH MPEP 609; DRAW LINE THROUGH CITATION IF NOT IN CONFORMANCE AND NOT CONSIDERED, INCLUDE COPY OF THIS FORM WITH NEXT COMMUNICATION TO APPLICANT.			